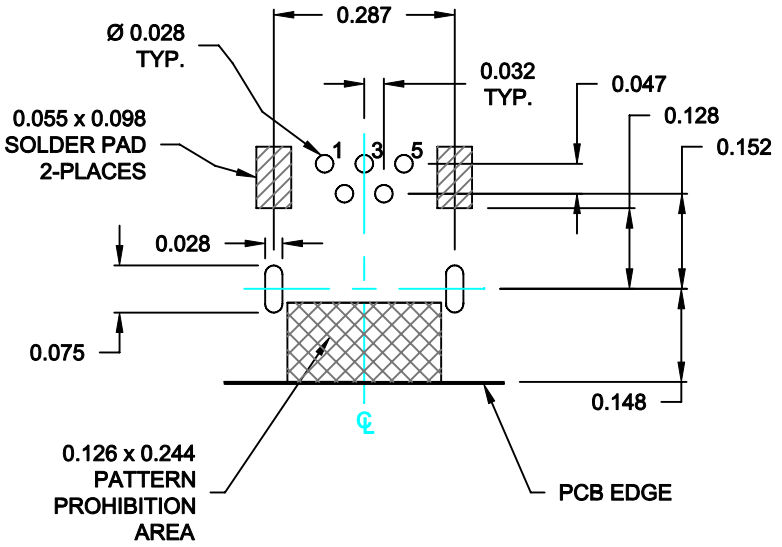
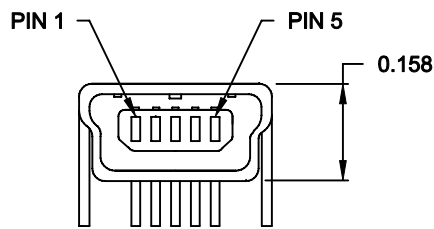
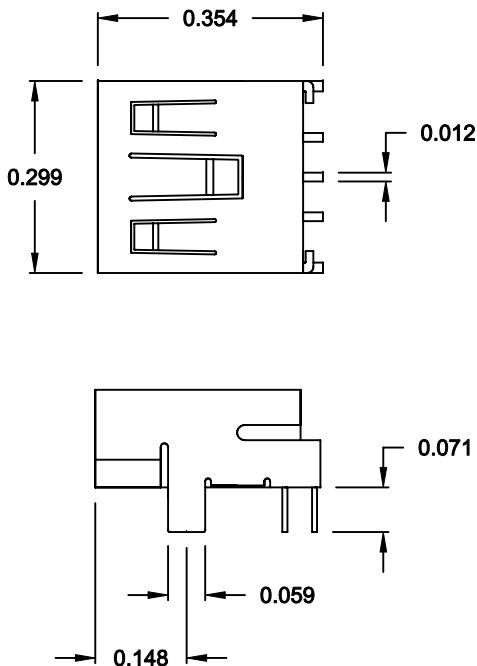


DESCRIPTION: USB MINI-B DIP SOLDER



RECOMMENDED PCB LAYOUT
SCALE = 3 : 1

ELECTRICAL:

- CONTACT CURRENT RATING: 1.0 AMPS
- DIELECTRIC WITHSTANDING VOLTAGE: 100VAC
- INSULATION RESISTANCE: 100 MegOhms Min.
- CONTACT RESISTANCE: 30 MilliOhms Max.
- OPERATING TEMPERATURE: -25°C TO +70°C

MECHANICAL:

- MATING FORCE: 3.5 Kg Max.
- UNMATING FORCE: 0.5 Kg Min.

MATERIALS:

- CONTACTS: PHOSPHOR BRONZE
- INSULATOR: THERMOPLASTIC PA9T UL 94V-0
- SHELL: BRASS

PLATING:

- CONTACTS: 30u" GOLD (MATING AREA)
TIN (LEAD FREE) SOLDER TAILS
- SHELL: NICKEL PLATED
- USB VERSION: 2.0

DO NOT SCALE FROM DRAWING

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			CHECKED:	DATE:
<h1>NorComp</h1>		SCALE:	SHEET 1 OF 1	REV 1
		DWG NO. 065-005-121R010		

RoHS COMPLIANT